USB PD Source Controller with 32-bit RISC-V MCU

Hynetek Semiconductor Co., Ltd.

HUSB362

ADVANCE INFORMATION

FEATURES

- USB Type-C PD Source with PPS Supported
  - Compliant with USB Type-C Specification Reversion 2.1
- 28 V EPR FPDO and EPR AVS Supported
- Integrated VCONN Power for eMarker Detection
- Both N-MOS and P-MOS Supported
- Multiple DPDM Charging Protocols Implemented
  - BC1.2 DCP and Divider 3
  - QC2.0, QC3.0, AFC, FCP and UFCS
- Up to 35 V Maximum Voltage Rating at USB Type-C Connector Pins
- Programmable Constant Voltage and Constant Current Control
- Fault Protections including Over-voltage Protection, Over-current Protection, Short Circuitry Protection, Over-temperature Protection, Under-voltage Protection, CC Over-voltage Protection, DPDM Over-voltage Protection, Thermal Shut Down
- 32-bit RISC-V MCU with 32 kB MTP Memory
- Sleep Mode Supported
- ±4 kV HBM ESD Rating for all of Type-C Connector Pins

APPLICATIONS

Travel Adaptor

Car Charger

GENERAL DESCRIPTION

HUSB362 is designed for a USB Type-C PD Source product. It can support up to multiple PDOs with programmable voltage and current for different applications, such as PPS PDOs, EPR PDOs. All of PDOs are fully compliant with USB PD 3.1 Specification Rev.1.4.

Besides, HUSB362 implements DPDM charging protocols. Both D+ and D- pins can be configured to support QC2.0, QC3.0, AFC, FCP, UFCS and divider 3 mode which provide excellent compatibility for the legacy devices.

It integrates an GATE driver to enable the VBUS from VIN to protect the devices connected with Type-C connector.

Only 300uA operation current is needed for HUSB362 during sleep mode. The high voltage tolerance and protections at CC1, CC2, D+ and D- pins provides more reliability for the system.

TYPICAL APPLICATION CIRCUIT

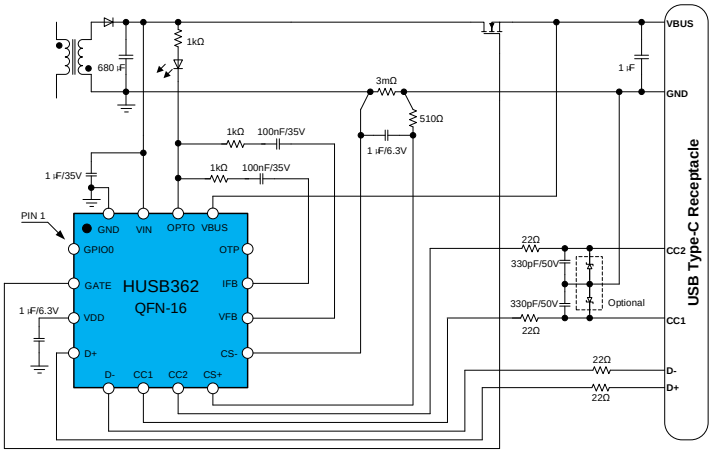

Figure 1. Typical Application Circuit

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REVISION HISTORY

Version	Date	Owner	Descriptions
Rev. 0.0	07/2022	Yingyang Ou	Initial version

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

TOP VIEW

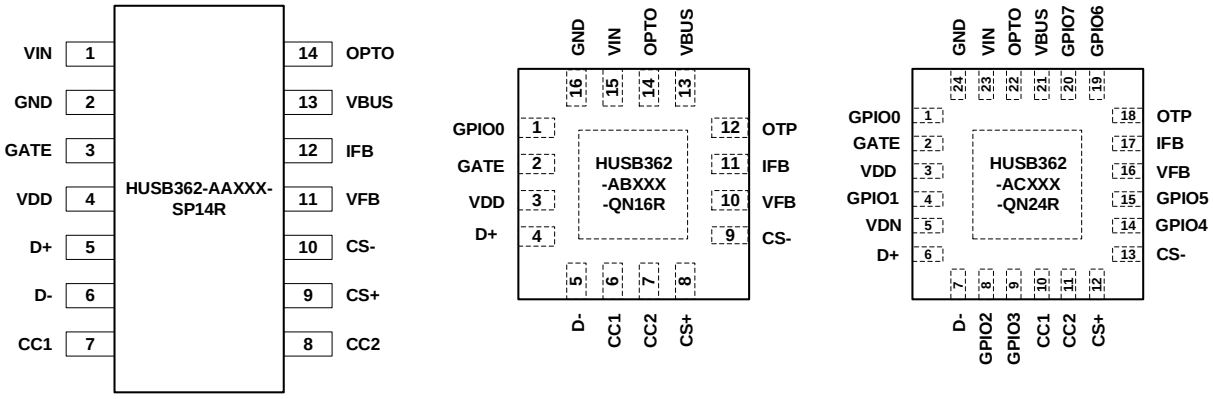

Figure 2. HUSB362 Pin Assignment

Table 1. HUSB362-AAXXX-SP14R Pin Function Descriptions

Pin No.	Pin Name	Type[1]	Description
1	VIN	P	Supply voltage input. Connect this pin to GND via a recommended 1μF ceramic capacitor.
2	GND	P	Power ground.
3	GATE	AO	N-MOSFET Gate driver output for VBUS load switch.
4	VDD	P	Internal 1.5 V regulator output for system power. Connect a 1μF ceramic capacitor at this pin.
5	D+	DIO	USB D+ line.
6	D-	DIO	USB D- line.
7	CC1	AIO	USB Type-C CC1 line.
8	CC2	AIO	USB Type-C CC2 line.
9	CS+	AI	Positive input of the current sense amplifier.
10	CS−	AI	Negative input of the current sense amplifier.
11	VFB	AI	Feedback point of Constant Voltage (CV) loop, connect CV compensation network to this pin.
12	IFB	AI	Feedback point of Constant Current (CC) loop, connect CC compensation network to this pin.
13	VBUS	AI	VBUS sense and discharge pin.
14	OPTO	AI	OPTO driver. Connect to the opto-coupler in isolated ACDC applications.

Table 2. HUSB362-ABXXX-QN16R Pin Function Descriptions

Pin No.	Pin Name	Type	Description
1	GPIO0	AO	General purpose pin 0. This pin is only open drain output.
2	GATE	AO	N-MOSFET Gate driver output for VBUS load switch.
3	VDD	P	Internal 1.5 V regulator output for system power. Connect a 1μF ceramic capacitor at this pin.
4	D+	DIO	USB D+ line.
5	D-	DIO	USB D- line.
6	CC1	AIO	USB Type-C CC1 line.
7	CC2	AIO	USB Type-C CC2 line.
8	CS+	AI	Positive input of the current sense amplifier.
9	CS−	AI	Negative input of the current sense amplifier.
10	VFB	AI	Feedback point of Constant Voltage (CV) loop, connect CV compensation network to this pin.

ADVANCE INFORMATION

Pin No.	Pin Name	Type	Description
11	IFB	AI	Feedback point of Constant Current (CC) loop, connect CC compensation network to this pin.
12	OTP	AI	External temperature sensing pin. An internal pull up current source is connected at this pin. A NTC thermistor is recommended to be place at this pin.
13	VBUS	AI	VBUS sense and discharge pin.
14	OPTO	AI	OPTO driver. Connect to the opto-coupler in isolated ACDC applications.
15	VIN	P	Supply voltage input. Connect this pin to GND via a recommended 1μF ceramic capacitor.
16	GND	P	Power ground.
-	PAD	-	QFN package pad. It is recommended to connect this pin to GND.

Table 3. HUSB362-ACXXX-QN24R Pin Function Descriptions

Pin No.	Pin Name	Type	Description
1	GPIO0	AO	General purpose pin 0. This pin is only open drain output.
2	GATE	AO	N-MOSFET Gate driver output for VBUS load switch.
3	VDD	P	Internal 1.5 V regulator output for system power. Connect a 1μF ceramic capacitor at this pin.
4	GPIO1	AO	General purpose pin 1. This pin is only open drain output.
5	VDN	AI	ADC input pin for voltage detection.
6	D+	DIO	USB D+ line.
7	D-	DIO	USB D- line.
8	GPIO2	DIO	General purpose pin 2. This pin can be configured as ADC input, digital input, digital output, pull up or pull down function by firmware.
9	GPIO3	DIO	General purpose pin 3. This pin can be configured as ADC input, digital input, digital output, pull up or pull down function by firmware.
10	CC1	AIO	USB Type-C CC1 line.
11	CC2	AIO	USB Type-C CC2 line.
12	CS+	AI	Positive input of the current sense amplifier.
13	CS−	AI	Negative input of the current sense amplifier.
14	GPIO4	AO	General purpose pin 4. This pin is only open drain output.
15	GPIO5	AO	General purpose pin 5. This pin is only open drain output.
16	VFB	AI	Feedback point of Constant Voltage (CV) loop, connect CV compensation network to this pin.
17	IFB	AI	Feedback point of Constant Current (CC) loop, connect CC compensation network to this pin.
18	OTP	AI	External temperature sensing pin. An internal pull up current source is connected at this pin. A NTC thermistor is recommended to be place at this pin.
19	GPIO6	DIO	General purpose pin 6. This pin can be configured as ADC input, digital input, digital output, pull up or pull down function by firmware.
20	GPIO7	DIO	General purpose pin 7. This pin can be configured as ADC input, digital input, digital output, pull up or pull down function by firmware.
21	VBUS	AI	VBUS sense and discharge pin.
22	OPTO	AI	OPTO driver. Connect to the opto-coupler in isolated ACDC applications.
23	VIN	P	Supply voltage input. Connect this pin to GND via a recommended 1μF ceramic capacitor.
24	GND	P	Power ground.
-	PAD	-	QFN package pad. It is recommended to connect this pin to GND.

ADVANCE INFORMATION

1 Legend:
A = Analog Pin
P = Power Pin
D = Digital Pin
I = Input Pin
O = Output Pin

RECOMMENDED OPERATING CONDITIONS

Table 4.

Parameter	Rating
VIN Input Voltage	3.15 V to 29.4 V
Operating Junction Temperature Range (T_J)	−40 °C to 125 °C
Ambient Temperature Range (T_A)	-40 °C to 85 °C

SPECIFICATIONS

V_{IN} = 3.15 V to 29.4 V, T_J = −40°C to 125°C for minimum and maximum specifications, and T_A = 25°C for typical specifications, unless otherwise noted.

Table 5. Electrical Characteristics

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
Power Supply						
Supply Voltage UVLO Threshold	V_{IN_UVLO}	Rising edge		3		V
Supply Voltage UVLO Hysteresis	$V_{IN\_UVLO\_HYS}$			300		mV
Operation Mode Supply Current	I_{CC_OPR}	CC is attached with a R_d, normal operation		4		mA
Sleep Mode Supply Current	I_{CC_SLP}	CC is attached with a R_d, configured in sleep mode			1.5	mA
Quiescent Current	I_Q	CC1 and CC2 pins are floating		300		µA
Internal Regulator (VDD)						
Output Voltage	V_{DD}			1.3		V
Type C Function (CC1, CC2)						
Default Current Source	I_{RP_DFT}		64	80	96	µA
1.5 A Current Source	$I_{RP\_1.5A}$		166	180	194	µA
3 A Current Source	I_{RP_3A}		304	330	356	µA
Rd Detection Threshold 1	$v_{Rd\_OPEN\_1.5A}$	Default or 1.5 A R_p current source is enabled, T_A = 25°C	1.55	1.6	1.65	V
Rd Detection Threshold 2	$v_{Rd\_OPEN\_3A}$	3 A R_p current source is enabled, T_A = 25°C	2.55	2.6	2.65	V
Ra Detection Threshold 0	v_{Ra_DEF}	Default R_p current source is enabled, T_A = 25°C	0.15	0.2	0.25	V
Ra Detection Threshold 1	$v_{Ra\_1.5A}$	1.5 A R_p current source is enabled, T_A = 25°C	0.35	0.4	0.45	V
Ra Detection Threshold 2	v_{Ra_3A}	3 A R_p current source is enabled, T_A = 25°C	0.75	0.8	0.85	V
CC Impedance in Disable Mode	R_{P_DIS}	CC impedance with R_P is disabled	2			MΩ
VCONN Output Voltage	v_{VCONN}	VCONN is enabled	3	5	5.5	V
VCONN Output Current Limit	I_{VCONN}	V_{IN} = 3.3 V to 5.5 V and VCONN is enabled	20			mA
Type C PD BMC Receiver						
Noise Amplitude when BMC is Active	$v_{NoiseActive}$	Peak-to-peak noise after Rx filter has been applied			165	mV
Noise Amplitude when BMC is Idle	$v_{NoiseIdle}$	Peak-to-peak noise after Rx filter has been applied			300	mV
Receiver Input Impedance	z_{BmcRx}	Input impedance of Rx	2			MΩ
Rx Bandwidth Limiting Filter	$t_{RxFilter}$	Time constant of a single pole filter	100			ns
Type C PD BMC Transmitter						

ADVANCE INFORMATION

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
Bit Rate	$f_{BitRate}$	Refer the average bit rate of the last 32b of the Preamble	270	300	330	kbps
Unit Interval	UI		3.03	3.33	3.7	μs
Bitrate Drift	$p_{BitRate}$				0.25	%
Fall Time	t_{Fall}	10% and 90% amplitude points, unloaded condition	300			ns
Rise Time	t_{Rise}	10% and 90% amplitude points, unloaded condition	300			ns
Voltage Swing	v_{Swing}	CC pull down resistor >800 Ω	1.05	1.125	1.2	V
Voltage Low	v_{Low}	CC pull down resistor >800 Ω	-75	0	75	mV
Transmitter output impedance	z_{Driver}		33	50	75	Ω
BC1.2 DCP MODE						
D+ and D- Shorting Resistance	R_{DPM_SHORT}	V_{D+} = 0.6 V		30		Ω
D+ Leakage Resistance	R_{DP_LKG}	V_{D+} = 0.6 V		800		kΩ
D- Leakage Resistance	R_{DM_LKG}	V_{D-} = 0.6 V		800		kΩ
DIVIDER 3 MODE						
D+ Output Voltage	$V_{DP\_2.7V}$	V_{IN} = 5 V		2.7		V
D- Output Voltage	$V_{DM\_2.7V}$	V_{IN} = 5 V		2.7		V
D+ Output Impedance	R_{DP_PAD}	I_{D+} = −5 μA		30		kΩ
D- Output Impedance	R_{DM_PAD}	I_{D-} = −5 μA		30		kΩ
HVDCP MODE						
Output Voltage Selection Reference	V_{SEL_REF}			2.0		V
Data Detect Voltage	V_{DAT_REF}			0.325		V
D- Pull-Down Resistance	R_{DM_DWM}			15		kΩ
FCP MODE						
D- FCP TX Valid Output High	V_{TX_VOH}		2.55		3.6	V
D- FCP TX Valid Output Low	V_{TX_VOL}				0.3	V
D- FCP RX Valid Input High	V_{RX_VIH}		1.4		3.6	V
D- FCP RX Valid Input Low	V_{RX_VIL}				1	V
Unit Interval for FCP	UI			160		μs
Voltage Regulation						
VDAC LSB	LSB_VDAC					
Default Voltage	$V_{DEFAULT}$		4.75	5.1	5.5	V
Regulation Accuracy	$v_{SRCValid}$	T_A = 25°C	99	100	101	%
		T_J = -40°C to 125°C	97	100	103	%
Active Load for Discharge	R_{ALD}	ALD option 0 is selected		100		mA
		ALD option 1 is selected		150		mA
		ALD option 2 is selected		200		mA
		ALD option 3 is selected		250		mA
Current Control						
Constant Current Accuracy		Operating current is less than 3 A	-0.15	0	0.15	A
		Operating current is higher than 3 A, refer to nominal operation current	95	100	105	%
Current Sensing Resistor	R_{CS}			3		mΩ
Gate Driver and VBUS						
Gate Driver Output Voltage	V_{GATE}	V_{IN} ≤ 21 V	5	7	10	V

ADVANCE INFORMATION

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
		V_{IN} > 21 V	4.5	5.5	6.5	V
Gate Driver Output Current	I_{GATE_ON}			20		µA
Gate Discharge Current	I_{GATE_DSG}			20		mA
VBUS Discharge Current	I_{VBUS_DSG}			20		mA
Fault Protection						
Over-voltage Protection Threshold	V_{IN_OV}	OVP threshold option 0, refer to nominal V_{IN}		110		%
		OVP threshold option 1, refer to nominal V_{IN}		115		%
		OVP threshold option 2, refer to nominal V_{IN}		120		%
		OVP threshold option 3, refer to nominal V_{IN}		125		%
Over-current Protection Threshold	I_{IN_OCP}	Nominal output current = 3 A		3.6		A
Short-circuit Protection Threshold	I_{IN_SCP}			12		A
OTP Current Source	I_{OTP}			80		µA
Thermal Shut Down Threshold	T_{SD}			150		°C
Thermal Shut Down Hysteresis	T_{SDHys}			20		°C
ADC						
ADC Resolution	N_{ADC}			11		Bit
ADC Reference Voltage	V_{ADC}			2.5		V
ADC Sample Rate	f_{ADC}			125		kHz
GPIO						
Digital Output High Voltage	V_{OH_D}	Source current = 2 mA		3.3		V
Digital Output Low Voltage	V_{OL_D}	Sink current = 2 mA			0.4	V
Digital Input High Voltage	V_{IH_D}		1.4			V
Digital Input Low Voltage	V_{IL_D}				1	V
Internal Pull-up Resistor	R_{GPIO_PU}			35		kΩ
Internal Pull-down Resistor	R_{GPIO_PD}			35		kΩ

ADVANCE INFORMATION

ABSOLUTE MAXIMUM RATINGS

Table 6.

Parameter	Rating
VIN, VBUS, OPTO, GATE to GND	−0.3 V to 35 V
CC1, CC2, D+, D-, CS+, CS- to GND	−0.3 V to 30 V
VFB, IFB,VDN, OTP, GPIO0, GPIO1, GPIO2, GPIO3, GPIO4, GPIO5, GPIO6, GPIO7 to GND	−0.3 V to 7 V
VDD to GND	−0.3 V to 2 V
Junction Temperature Range	−40°C to 125°C
Soldering Conditions	JEDEC J-STD-020
Electrostatic Discharge (ESD)	
Human Body Model (GATE, CC1, CC2, D+, D- and VBUS pins)	±4000 V
Human Body Model (Other pins)	±2000 V
Charged Device Model	±500 V

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to printed circuit board (PCB) design and operating environment. Close attention to PCB thermal design is required.

θ_{JA} is the natural convection junction to ambient thermal resistance measured in a one cubic foot sealed enclosure.

θ_{JC} is the junction to case thermal resistance.

Table 7. Thermal Resistance

Package Type	θ_{JA}	θ_{JC}	Unit
QFN4x4-16L	TBD	TBD	°C/W
QFN4x4-24L	TBD	TBD	°C/W
SOP-14L	TBD	TBD	°C/W

ESD CAUTION

Electrostatic Discharge Sensitive Device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

ADVANCE INFORMATION

FUNCTIONAL BLOCK DIAGRAM

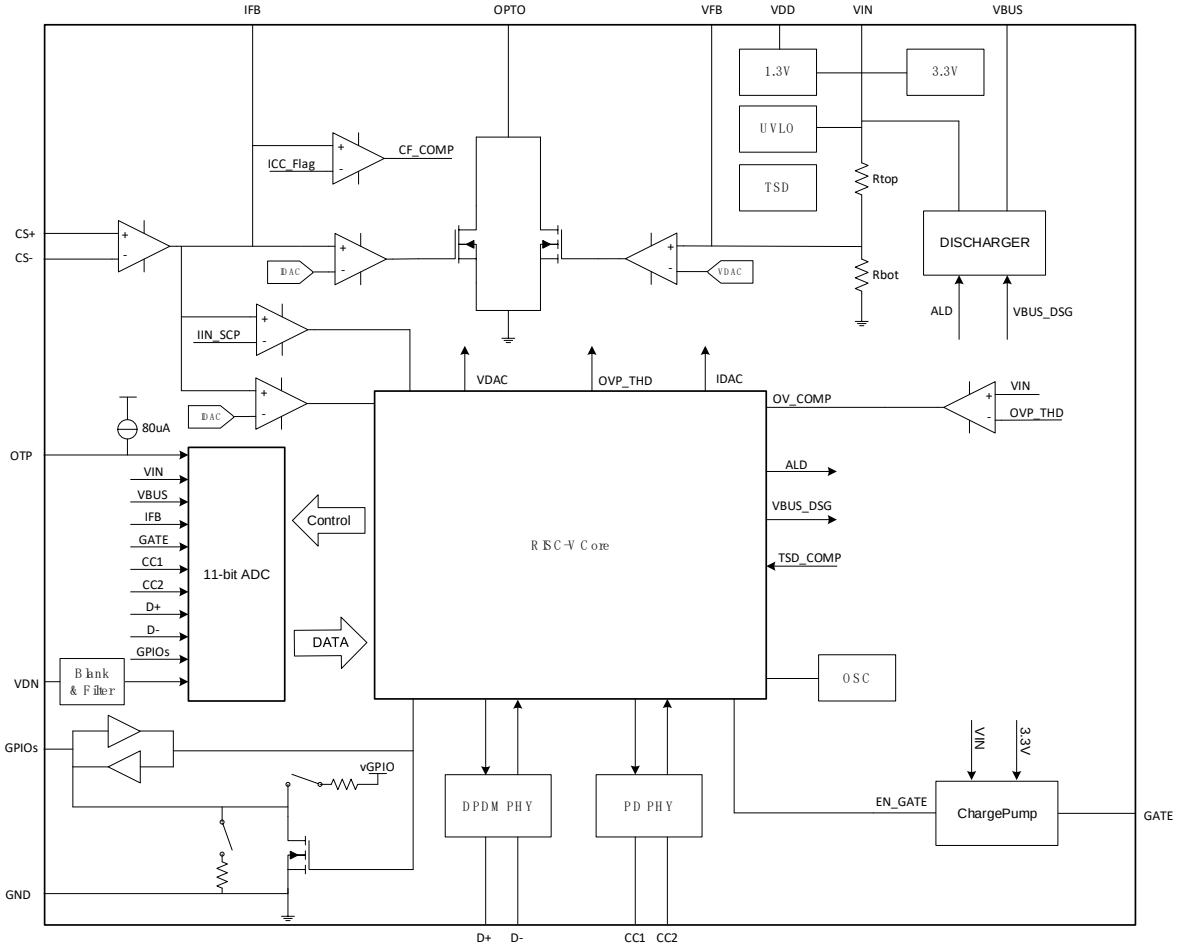

Figure 3. HUSB362 Functional Block Diagram

ADVANCE INFORMATION

THEORY OF OPERATION

HUSB362 is a MCU-based USB PD Source controller. It integrates a MCU core with necessary functions for USB PD protocol, legacy charging protocols and power regulation. By modifying the firmware, the HUSB362 can be employed in different applications. The integrated protections including OCP, OVP, UVP, SCP, OTP, CCOV, TSD and DPDMOV can enhance the system reliability significantly.

MCU

HUSB362 integrates a 32-Bit RISC-V MCU core for the main operation. This subsystem implements the standard RISC-V structure. It features:

- Support RV32 commands
- Support the programs in C format
- Support interruptions
- Internal communication BUS
- With 8kB ROM, 8kB RAM, 32kB Flash peripherals

VIN PIN

VIN pin is the power supply input, which is derived from the output of the AC-DC or DC-DC converter. Connect a 1 μF decoupling MLCC between VIN pin and GND pin.

The VIN pin is also connected to an internal MOSFET and discharge resistor, which is used as a bleeder to help discharge the energy stored in the output capacitor. With this bleeder, VIN can be regulated to vSafe5V upon the detachment of a connected device, or to a lower desired output voltage level upon a request command received from the Sink, such as from 20 V to 5 V.

VDD PIN

An internal liner regulator is used to provide 1.3 V for internal circuits. Connect a 1μF MLCC to VDD pin for decoupling.

CONTROL LOOP COMPENSATION CIRCUIT (VFB, CS+, CS−, IFB, OPTO PINS)

In the HUSB362, the constant voltage loop (CV loop) compensation and constant current loop (CC loop) compensation are implemented. VIN voltage is scaled by a resistor divider to be as the feedback voltage. It is compared with the internal voltage reference to generate an error signal. The CV loop can compensate this error signal. And then the compensated signal is employed to drive the primary side of the opto-coupler and control the AC-DC power loop.

CURRENT SENSE RESISTOR

The recommended current sense resistor is 3 mΩ. The sensed current information is employed to perform OCP, SCP and Constant Current Control.

CC1 AND CC2 PINS

CC1 and CC2 pins are used to detect Type-C connection, BMC communication.

TYPE-C CC FUNCTION

CC1 and CC2 are the Configuration Channel pins used for connection and attachment detection, plug orientation determination and system configuration management across USB Type-C cable.

The HUSB362 monitors the status of CC1 and CC2 pins and decide which state the HUSB362 should enter.

CC1 and CC2 are configured as Source only mode with 1.5 A and 3 A current advertising. The default R_p current on CC1 and CC2 is I_{CC_3P0}, which means 3 A current advertising.

The CC1 and CC2 can tolerance a voltage up to 30 V. This is helpful for the HUSB362 to survive in the failure when the CC1 or CC2 is shorted to the VBUS pin.

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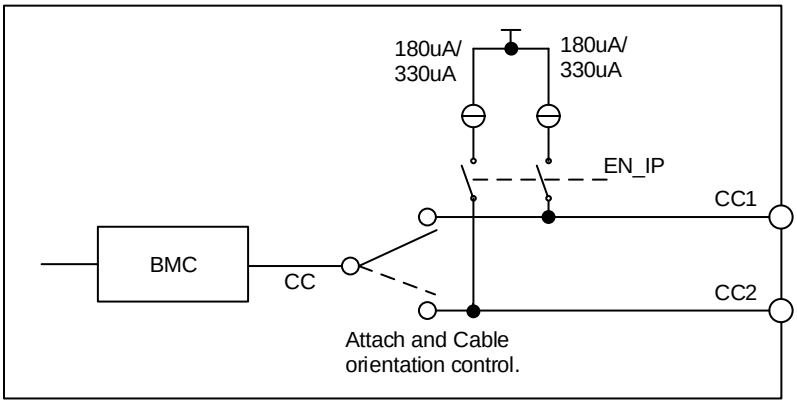


Figure 4. CCx Hardware Diagram

BMC DRIVER

Through the Type-C detection, one of the CC pins will be connected to the internal BMC block to achieve PD communication.

VBUS PIN

This pin is used to sense VBUS presence and discharge VBUS voltage on USB Type-C receptacle side.

The VBUS pin is also connected to an internal MOSFET and discharging circuitry, which is used as a bleeder to help dissipate the energy stored in the VBUS capacitor. With this bleeder, VBUS is discharged to vSafe0V upon the detachment of a connected device, or to a lower desired output voltage level upon a request command received from the Sink, such as from 20 V to 5 V.

GATE PIN

The GATE pin of the HUSB362 is designed to drive an external N-MOSFET. When the HUSB362 is attached and is ready to enable VBUS. The GATE pin outputs a voltage to turn on the external N-MOSFET. The turn on time of the external N-MOSFET may impacted by the external N-MOSFET's characteristics.

OVER VOLTAGE PROTECTION

The HUSB362 detects the VIN pin voltage to achieve over-voltage protection function. The threshold to trigger over-voltage protection can be configured as 4 options. When the over-voltage condition occurs, the firmware is notified to handle this fault.

OVER CURRENT PROTECTION

When the current sensed by the sense resistor exceeds the pre-set threshold in firmware, The threshold to trigger over-current protection can be configured by firmware. When the over-current condition occurs, the firmware is notified to handle this fault.

SHORT CIRCUIT PROTECTION

The HUSB362 integrates SCP protection function. When the VBUS is hard shorted to GND by fault, the output current increases sharply. When the output current reaches the SCP threshold, the firmware is notified to handle this fault.

OVER TEMPERATURE PROTECTION

The HUSB362 integrates a current source at OTP pin. When the OTP function is preferred, a NTC thermistor is recommended to be place at OTP pin. In addition, the internal current source outputs the current to the GND through the external thermistor. The voltage at the OTP pin can be sampled by ADC to identify the actual temperature.

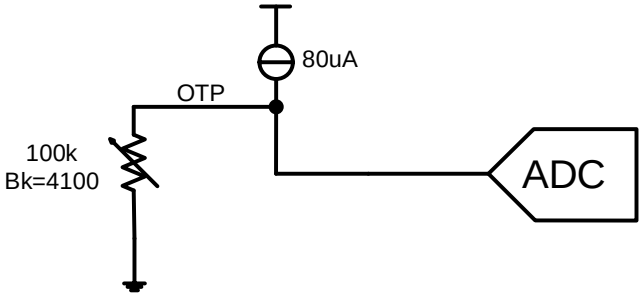


Figure 5. OTP Detection

THERMAL SHUT DOWN

When the junction temperature rises across T_{TSD}, thermal shut down takes action and the GATE is disabled. When the junction temperature falls across T_{TSD}-T_{TSD_HYS}, the HUSB362 is reset to default mode and will automatic recover again.

ANALOG-DIGITAL CONVERTER

The HUSB362 supports various fast charging protocols including BC1.2 DCP, Divider 3, QC 2.0/3.0 Class A, AFC, FCP and SCP. According to the different status of D+ and D- pins, the HUSB362 recognizes the attached Sinks and apply the fast charging protocol automatically.

GPIO

GPIO pins are for general purpose. GPIO pins can be configured in different work mode per the firmware settings. GPIO pins can be worked as:

Interrupt Input: the GPIO pin is a digital input pin, any digital logic level transition of GPIO pin can be configured a interrupt source to notify the MCU.

Output Pin: the GPIO pin is a digital output pin, the output state can be determined by the firmware.

ADC Input: the GPIO pin is an analog input pin, the input voltage can be sampled by ADC and reported to the MCU..

ADVANCE INFORMATION

TYPICAL APPLICATION CIRCUITS

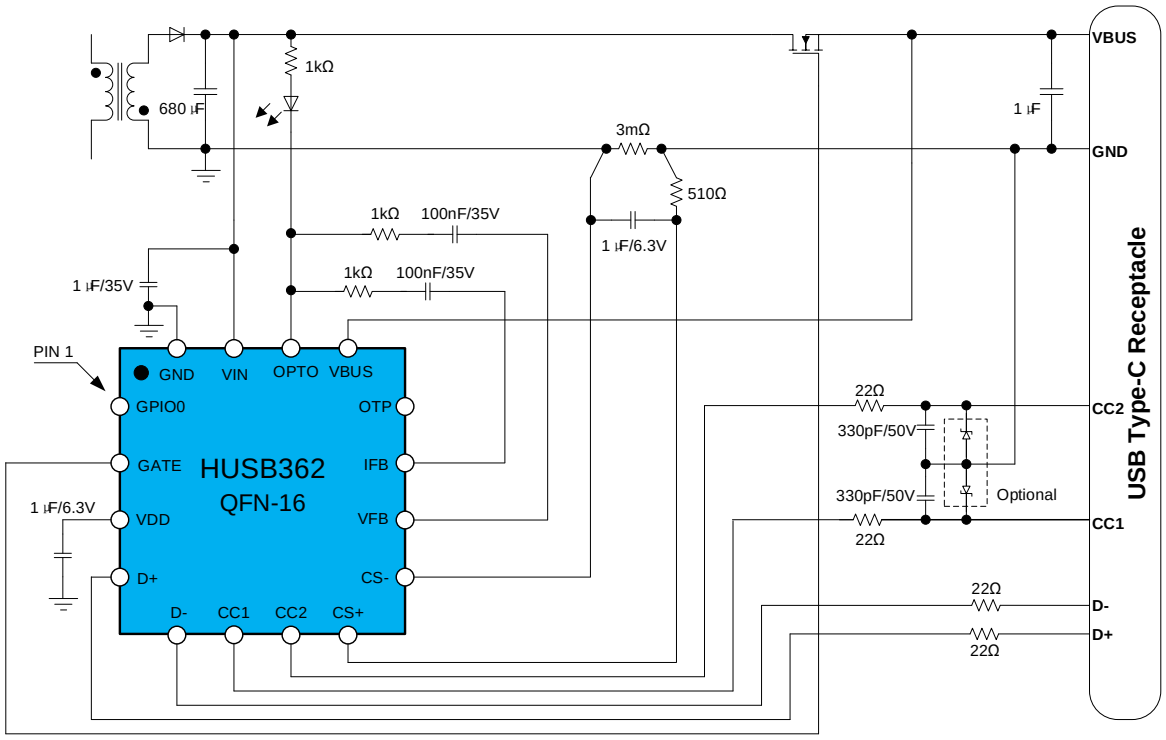
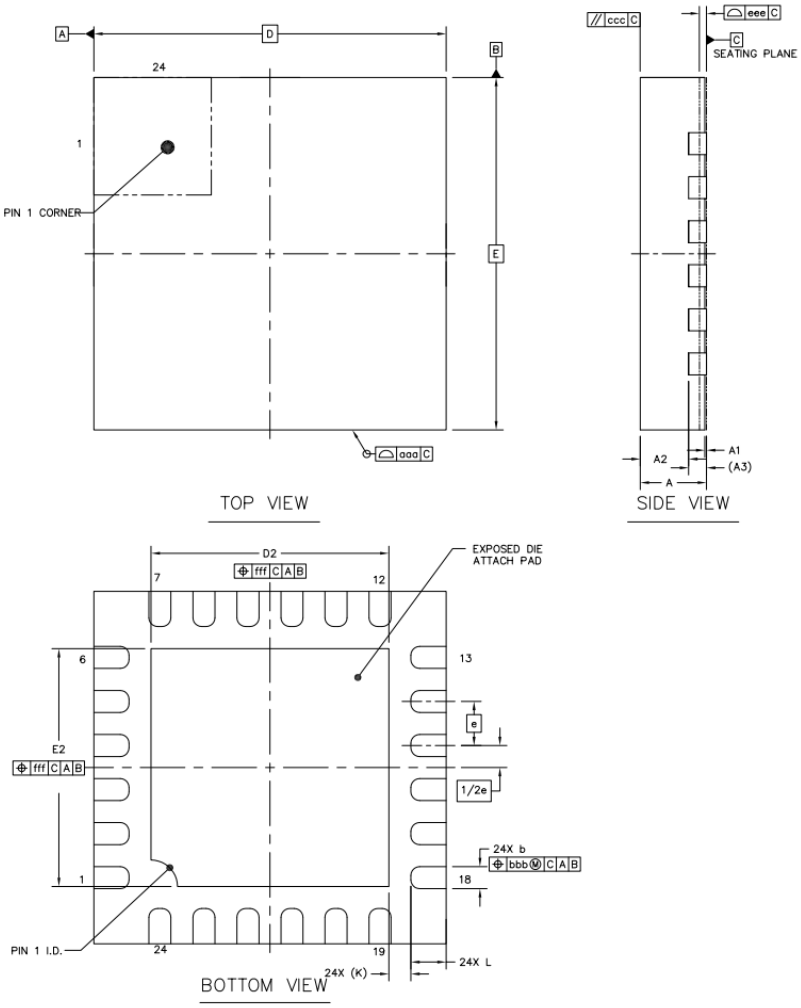


Figure 6. Typical Application

ADVANCE INFORMATION

PACKAGE OUTLINE DIMENSIONS



		SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS		A	0.7	0.75	0.8
STAND OFF		A1	0	0.02	0.05
MOLD THICKNESS		A2	---	0.55	---
L/F THICKNESS		A3		0.203 REF	
LEAD WIDTH		b	0.2	0.25	0.3
BODY SIZE	X	D		4 BSC	
	Y	E		4 BSC	
LEAD PITCH		e		0.5 BSC	
EP SIZE	X	D2	2.6	2.7	2.8
	Y	E2	2.6	2.7	2.8
LEAD LENGTH		L	0.3	0.4	0.5
LEAD TIP TO EXPOSED PAD EDGE		K		0.2 min	
PACKAGE EDGE TOLERANCE		aaa		0.1	
MOLD FLATNESS		ccc		0.1	
COPLANARITY		eee		0.08	
LEAD OFFSET		bbb		0.1	
EXPOSED PAD OFFSET		fff		0.1	

Figure 7. QFN4x4-24L Package of Dimension

ADVANCE INFORMATION

ORDERING GUIDE

Model	Temperature Range	MSL	Package Type	Package Option
HUSB362-AA000-SP14R	-40 to 125°C	MSL3	SOP-14L	TBD
HUSB362-AB000-QN16R	-40 to 125°C	MSL3	QFN-16L, 4 mm x 4 mm	TBD
HUSB362-AC000-QN24R	-40 to 125°C	MSL3	QFN-24L, 4 mm x 4 mm	TBD

IMPORTANT NOTICE

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